

TI Bluetooth: Invalid RPA Leading to DoS for Bonded Devices (CVE-2023-52709)



1 Summary

Bluetooth resolvable Random Private Address (RPA) enables mitigations towards malicious third-parties from tracking a Bluetooth device while still allowing one or more already bonded devices (trusted parties) to identify the Bluetooth device of interest. The RPA address is *resolvable* using a key (referred to as Identity Resolving Key - IRK) shared with the already bonded devices.

One of the Bluetooth LE fuzz tests causes the Bluetooth LE DUT (device under test) using RPA for connectable advertising, to end up generating unresolvable RPAs after a while. This leads to causing DoS for the already bonded peer devices until the next valid RPA is generated (15 minutes by default).

2 Vulnerability

TI PSIRT ID

TI-PSIRT-2023-08198

CVE ID

CVE-2023-52709

CVSS Base Score

6.5

CVSS Vector

[CVSS:3.1/AV:A/AC:L/PR:N/UI:N/S:U/C:H/I:N/A:N](#)

Affected Products

Table 2-1. Affected Products

Device	Software Name	Software Version	BLE Stack Name	BLE Stack Version
CC2651P3, CC2651R3, CC2651R3SIPA, CC2642R, CC2642P, CC2652R, CC2652P, CC1352R, CC1352P, CC2652RSIP, CC2652PSIP, CC2642R-Q1, CC2652R7, CC2652P7, CC1352R7, CC1352P7	SIMPLELINK-CC13XX-CC26XX-SDK: SimpleLink™ software development kit (SDK)	V7.10.02.23 and earlier,	BLE5-Stack	v2.02.08.01 and earlier
CC2340R5, CC2340R5-Q1, CC230R2	SIMPLELINK-LOWPOWER-F3-SDK	v7.40.00.64 and earlier	BLE5-stack	v3.02.04.20 and earlier
CC2640R2F, CC2640R2L, CC2640R2F-Q1	SIMPLELINK-CC2640R2-SDK: SimpleLink™ CC2640R2 SDK - Bluetooth® low energy	v5.30.00.03 and earlier	BLE-Stack	v3.03.08.00 and earlier
			BLE5-Stack	v1.01.14.00 and earlier
CC1350	SIMPLELINK-CC13X0-SDK: SimpleLink™ Sub-1GHz CC13x0 Software Development Kit	v4.20.02.07 and earlier	BLE-Stack	v2.03.11.00 and earlier
CC2640, CC2650, CC2650MODA	N/A	v2.02.07.06 and earlier	BLE-STACK-2-X	v2.2.7 and earlier
CC2540, CC2541	N/A	v1.05.02.00 and earlier	BLE-STACK-1-X	v1.5.2 and earlier

Potentially Impacted Features

The potential vulnerability can impact Bluetooth Low Energy devices running the affected SDK versions and enabled Bluetooth privacy with resolvable private address feature.

Suggested Mitigations

The following SDK releases addresses the potential vulnerability:

Table 2-2. Suggested Mitigations

Affected SDK	First SDK Version with Mitigations	First BLE Stack Version with Mitigations
CC13XX-26XX-SDK, BLE5-STACK	SIMPLELINK-LOWPOWER-F2-SDK (7.40.00.77)	v2.02.09.00
CC2340 SDK, BLE5-STACK	SimpleLink Low Power F3 SDK (8.10.00.55)	v3.03.01.00
CC2640R2 SDK, BLE5-STACK	In upcoming release	In upcoming release
CC2640R2 SDK, BLE-STACK	In upcoming release	In upcoming release
CC1350, CC26x0, CC25x0 SDK, BLE-STACK	N/A ⁽¹⁾	N/A ⁽¹⁾

- Mitigation on these device stacks are not supported as this is a fix to the BLE stack in devices' ROM, and with limited ROM patch space on these devices, the patch memory is being reserved for more critical PSIRT tickets in the future. For questions, see psirt@ti.com.

Acknowledgments

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External References

- BLUETOOTH CORE SPECIFICATION, version 5.3
- [Bosch PSIRT Advisory](#)

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